

| Ref # | Hits | Search Query  | DBs             | Default Operator | Plurals | Time Stamp       |
|-------|------|---|-----------------|------------------|---------|------------------|
| S148  | 2    | MOSFET and plurality and lead and (resin adj molded adj package) and heat and sink  | USPAT           | OR               | ON      | 2005/02/18 11:36 |
| S149  | 1    | "5907474".PN.   | USPAT;<br>USOCR | OR               | ON      | 2005/02/18 11:35 |
| S150  | 1    | "6362964".PN.   | USPAT;<br>USOCR | OR               | ON      | 2005/02/18 11:35 |
| S151  | 1    | "6091341".PN.   | USPAT;<br>USOCR | OR               | ON      | 2005/02/18 11:35 |
| S152  | 1    | "5949649".PN.   | USPAT;<br>USOCR | OR               | ON      | 2005/02/18 11:35 |
| S153  | 1    | "4888307".PN.   | USPAT;<br>USOCR | OR               | ON      | 2005/02/18 11:36 |
| S154  | 1    | "4758927".PN.   | USPAT;<br>USOCR | OR               | ON      | 2005/02/18 11:36 |
| S155  | 2    | S148 and (semiconductor or device or molding or body or resin or lengthwise or direction or outside or located or leads or inner or outer or extracted or chip or die or plurality or metal or plate or mounting or electrical or slit or heat or sink or depression or bent or portion or metal or wire or bond or MISFET or MOSFET or output or watt or respective or tip or depressed or portions) | USPAT           | OR               | ON      | 2005/02/18 12:04 |
| S156  | 1    | ("6847112").PN.   | USPAT           | OR               | OFF     | 2005/02/18 12:03 |
| S157  | 1    | ("6703261").PN.   | USPAT           | OR               | OFF     | 2005/02/18 12:04 |
| S158  | 1    | S156 and (semiconductor or device or molding or body or resin or lengthwise or direction or outside or located or leads or inner or outer or extracted or chip or die or plurality or metal or plate or mounting or electrical or slit or heat or sink or depression or bent or portion or metal or wire or bond or MISFET or MOSFET or output or watt or respective or tip or depressed or portions) | USPAT           | OR               | ON      | 2005/02/18 12:05 |

2/18/05

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|------|---|---|-------|----|----|------------------|
| S159 | 1 | S149 and (semiconductor or device or molding or body or resin or lengthwise or direction or outside or located or leads or inner or outer or extracted or chip or die or plurality or metal or plate or mounting or electrical or slit or heat or sink or depression or bent or portion or metal or wire or bond or MISFET or MOSFET or output or watt or respective or tip or depressed or portions) | USPAT | OR | ON | 2005/02/18 12:06 |
| S160 | 1 | S150 and (semiconductor or device or molding or body or resin or lengthwise or direction or outside or located or leads or inner or outer or extracted or chip or die or plurality or metal or plate or mounting or electrical or slit or heat or sink or depression or bent or portion or metal or wire or bond or MISFET or MOSFET or output or watt or respective or tip or depressed or portions) | USPAT | OR | ON | 2005/02/18 12:07 |
| S161 | 1 | S151 and (semiconductor or device or molding or body or resin or lengthwise or direction or outside or located or leads or inner or outer or extracted or chip or die or plurality or metal or plate or mounting or electrical or slit or heat or sink or depression or bent or portion or metal or wire or bond or MISFET or MOSFET or output or watt or respective or tip or depressed or portions) | USPAT | OR | ON | 2005/02/18 12:08 |
| S162 | 1 | S152 and (semiconductor or device or molding or body or resin or lengthwise or direction or outside or located or leads or inner or outer or extracted or chip or die or plurality or metal or plate or mounting or electrical or slit or heat or sink or depression or bent or portion or metal or wire or bond or MISFET or MOSFET or output or watt or respective or tip or depressed or portions) | USPAT | OR | ON | 2005/02/18 12:08 |

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|----------|--------|---|-------|----|----|------------------|
| S16<br>3 | 1      | S153 and (semiconductor or device or molding or body or resin or lengthwise or direction or outside or located or leads or inner or outer or extracted or chip or die or plurality or metal or plate or mounting or electrical or slit or heat or sink or depression or bent or portion or metal or wire or bond or MISFET or MOSFET or output or watt or respective or tip or depressed or portions) | USPAT | OR | ON | 2005/02/18 12:10 |
| S16<br>4 | 1      | S154 and (semiconductor or device or molding or body or resin or lengthwise or direction or outside or located or leads or inner or outer or extracted or chip or die or plurality or metal or plate or mounting or electrical or slit or heat or sink or depression or bent or portion or metal or wire or bond or MISFET or MOSFET or output or watt or respective or tip or depressed or portions) | USPAT | OR | ON | 2005/02/18 12:28 |
| S16<br>5 | 243916 | "257"   | USPAT | OR | ON | 2005/02/18 12:42 |
| S16<br>6 | 2559   | 257/678   | USPAT | OR | ON | 2005/02/18 12:43 |
| S16<br>7 | 2184   | 257/700   | USPAT | OR | ON | 2005/02/18 12:43 |
| S16<br>8 | 1511   | 257/701   | USPAT | OR | ON | 2005/02/18 12:43 |
| S16<br>9 | 730    | 257/702   | USPAT | OR | ON | 2005/02/18 12:43 |
| S17<br>0 | 667    | 257/703   | USPAT | OR | ON | 2005/02/18 12:43 |
| S17<br>1 | 1222   | 257/704   | USPAT | OR | ON | 2005/02/18 12:43 |
| S17<br>2 | 451    | 257/705   | USPAT | OR | ON | 2005/02/18 12:43 |
| S17<br>3 | 2271   | 257/706   | USPAT | OR | ON | 2005/02/18 12:43 |
| S17<br>4 | 1885   | 257/707   | USPAT | OR | ON | 2005/02/18 12:44 |
| S17<br>5 | 1122   | 257/717   | USPAT | OR | ON | 2005/02/18 12:44 |
| S17<br>6 | 1467   | 257/718   | USPAT | OR | ON | 2005/02/18 12:44 |

|          |      |         |       |    |    |                  |
|----------|------|---------|-------|----|----|------------------|
| S17<br>7 | 1412 | 257/719 | USPAT | OR | ON | 2005/02/18 12:44 |
| S17<br>8 | 867  | 257/720 | USPAT | OR | ON | 2005/02/18 12:44 |
| S17<br>9 | 1189 | 257/727 | USPAT | OR | ON | 2005/02/18 12:44 |
| S18<br>0 | 949  | 257/728 | USPAT | OR | ON | 2005/02/18 12:44 |
| S18<br>1 | 447  | 257/729 | USPAT | OR | ON | 2005/02/18 12:44 |
| S18<br>2 | 891  | 257/730 | USPAT | OR | ON | 2005/02/18 12:44 |
| S18<br>3 | 332  | 257/731 | USPAT | OR | ON | 2005/02/18 12:44 |
| S18<br>4 | 1571 | 257/734 | USPAT | OR | ON | 2005/02/18 12:44 |
| S18<br>5 | 763  | 257/735 | USPAT | OR | ON | 2005/02/18 12:45 |
| S18<br>6 | 360  | 257/736 | USPAT | OR | ON | 2005/02/18 12:45 |
| S18<br>7 | 3011 | 257/737 | USPAT | OR | ON | 2005/02/18 12:45 |
| S18<br>8 | 2642 | 257/738 | USPAT | OR | ON | 2005/02/18 12:45 |
| S18<br>9 | 2356 | 257/777 | USPAT | OR | ON | 2005/02/18 12:45 |
| S19<br>0 | 1435 | 257/779 | USPAT | OR | ON | 2005/02/18 12:45 |
| S19<br>1 | 1918 | 257/780 | USPAT | OR | ON | 2005/02/18 12:45 |
| S19<br>2 | 1006 | 257/781 | USPAT | OR | ON | 2005/02/18 12:45 |
| S19<br>3 | 2047 | 257/784 | USPAT | OR | ON | 2005/02/18 12:45 |
| S19<br>4 | 585  | 257/785 | USPAT | OR | ON | 2005/02/18 12:45 |
| S19<br>5 | 2869 | 257/787 | USPAT | OR | ON | 2005/02/18 12:46 |
| S19<br>6 | 321  | 257/791 | USPAT | OR | ON | 2005/02/18 12:46 |